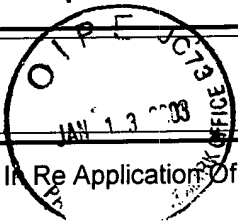


2827



**TRANSMITTAL LETTER
(General - Patent Pending)**

Docket No.
END920000187US1

In Re Application Of: **Richard R. Hall et al.**

Serial No.
09/884,778

Filing Date
06/19/2001

Examiner
Dinh, Tuan T.

Group Art Unit
2827

Title: **METHOD AND APPARATUS TO ESTABLISH CIRCUIT LAYERS INTERCONNECTIONS**

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TO THE COMMISSIONER OF PATENTS AND TRADEMARKS:

Transmitted herewith is:

**Amendment
Postcard**

in the above identified application.

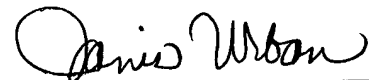
- ☒ No additional fee is required.
- ☐ A check in the amount of _____ is attached.
- ☒ The Commissioner is hereby authorized to charge and credit Deposit Account No. **09-0457 (IBM)** as described below. A duplicate copy of this sheet is enclosed.
- ☐ Charge the amount of _____
- ☒ Credit any overpayment.
- ☒ Charge any additional fee required.


Signature

Dated: **1/7/2003**

**Arlen L. Olsen
Reg. No. 37,543
SCHMEISER, OLSEN & WATTS
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Latham, NY 12110
(518) 220-1850**

I certify that this document and fee is being deposited on **1/7/2003** with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Commissioner of Patents and Trademarks, Washington, D.C. 20231.



Signature of Person Mailing Correspondence

Janis Urban

Typed or Printed Name of Person Mailing Correspondence

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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JAN 14 2003

TECHNOLOGY CENTER 2800

Applicants: Richard R. Hall *et al.*

Examiner: Dinh, Tuan T.

Serial No.: 09/884,778

Art Unit: 2827

Filed: 06/19/2001

Dkt. No.: END920000187US1

For: **METHOD AND APPARATUS TO
ESTABLISH CIRCUIT LAYERS INTERCONNECTIONS**

Commissioner for Patents
Washington, D.C. 20231

Sir:

This paper is being filed in response to the Final Office Action mailed November 7, 2002.

Applicant respectfully requests that the above-identified application be reconsidered in view of the Amendments and Remarks that follow, that each of the presently pending claims be allowed, and that the application be passed to issue.

Amendment

Please amend the above-referenced patent application as follows:

In The Specification:

Please delete the abstract and insert the following:

--An interconnect formed between layers of a circuit board, wherein a conductive element is embedded in an opening within a laminate of the circuit board, and wherein the conductive element forms at least one contact pad extending beyond a surface of the laminate.--

In The Claims

Claims 21-24 and 27-37 are pending in the application and are rejected.

Serial No. 09/884,778